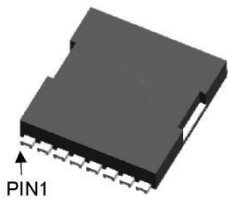


## SGT N-channel Power MOSFET

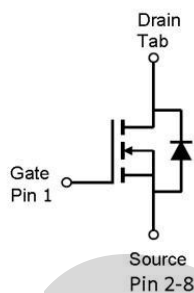
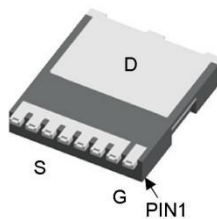
### MTR4R6N08TL

#### TOLL

TOLL Top View



TOLL Bottom View



$V_{DS}$	80	V
$R_{DS(on),TYP@ V_{GS}=10V}$	3.6	m $\Omega$
$I_D$	120	A

### Features

- 1、 Low on – resistance
- 2、 Package TOLL
- 3、 SGT N-channel Power MOSFET

### Applications

- 1、 Load Switch for Portable Devices
- 2、 DC/DC Converter

### Maximum ratings, at $T_A = 25^\circ\text{C}$ , unless otherwise specified

Symbol	Parameter	Rating	Unit	
V(BR)DSS	Drain-Source breakdown voltage	80	V	
VGS	Gate-Source voltage	$\pm 20$	V	
ID	Continuous drain current @VGS=10V	$T_C = 25^\circ\text{C}$ (Package limit)	120	A
		$T_C = 100^\circ\text{C}$	106	A
IDM	Pulse drain current tested ①	$T_C = 25^\circ\text{C}$	480	A
EAS	Avalanche energy, single pulsed ②		841	mJ
PD	Maximum power dissipation	$T_C = 25^\circ\text{C}$	208	W
TSTG,TJ	Storage and Junction Temperature Range		-55 to +150	$^\circ\text{C}$

## Thermal Characteristics

Symbol	Parameter	Typical	Unit
R $\theta$ JC	Thermal Resistance, Junction-to-Case	0.6	$^{\circ}\text{C}/\text{W}$
R $\theta$ JA	Thermal Resistance, Junction-to-Ambient	62	$^{\circ}\text{C}/\text{W}$

## Electrical Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
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### Static Electrical Characteristics @ T<sub>j</sub>=25 $^{\circ}\text{C}$ (unless otherwise stated)

V(BR)DSS	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250 $\mu\text{A}$	80	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> =80V, V <sub>GS</sub> =0V	--	--	1	$\mu\text{A}$
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> = $\pm 20\text{V}$ , V <sub>DS</sub> =0V	--	--	$\pm 100$	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 $\mu\text{A}$	2.0	3.0	4.0	V
R <sub>DS(on)</sub>	Drain-Source On-State Resistance ④	V <sub>GS</sub> =10V, I <sub>D</sub> =50A	--	3.6	4.6	m $\Omega$
g <sub>fs</sub>	Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =50A	170	--	--	S

### Dynamic Electrical Characteristics @ T<sub>j</sub> = 25 $^{\circ}\text{C}$ (unless otherwise stated)

C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =40V, V <sub>GS</sub> =0V, f=1MHz	--	5154	--	pF
C <sub>oss</sub>	Output Capacitance		--	783	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	49	--	pF
R <sub>g</sub>	Gate Resistance	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz	--	1.4	--	$\Omega$
Q <sub>g</sub> (10V)	Total Gate Charge	V <sub>GS</sub> =10V, V <sub>DS</sub> =40V, I <sub>D</sub> =30A, I <sub>D</sub> =20A	--	64	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	19	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	17	--	nC

## Switching Characteristics

Td(on)	Turn-on Delay Time	VGS=10V, VDS=50V, RL=3.0Ω, Tj=25°C	--	26	--	ns
Tr	Turn-on Rise Time		--	47	--	ns
Td(off)	Turn-Off Delay Time		--	54	--	ns
Tf	Turn-Off Fall Time		--	28	--	ns

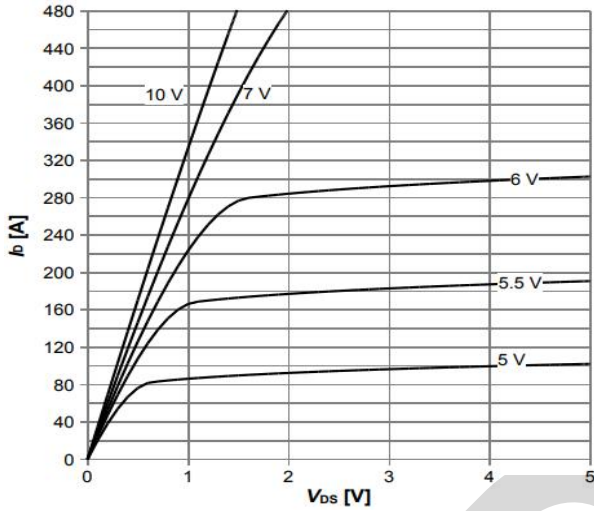
## Source- Drain Diode Characteristics@ Tj = 25°C (unless otherwise stated)

VSD	Forward on voltage	ISD=50A, VGS=0V	--	0.8	1.2	V
Trr	Reverse Recovery Time	IF=30A, di/dt=500A/μs	--	66	--	ns
Qrr	Reverse Recovery Charge	IF=30A, di/dt=500A/μs	--	80	--	nC

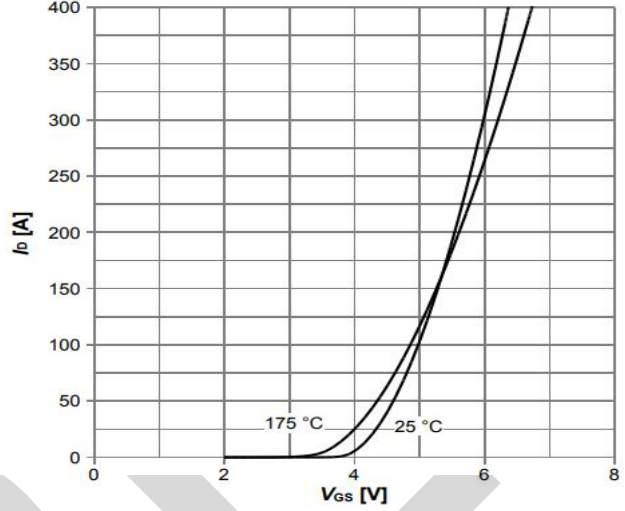
- NOTE: ① Repetitive rating; pulse width limited by max junction temperature.  
 ② Limited by T<sub>Jmax</sub>, starting T<sub>J</sub> = 25°C, L = 0.5mH, R<sub>G</sub> = 25Ω. Part not recommended for use above this value  
 ③ The power dissipation P<sub>DSM</sub> is based on R<sub>θJA</sub> and the maximum allowed junction temperature of 150°C.  
 ④ Pulse width ≤ 380μs; duty cycle ≤ 2%.

## Typical Performance Characteristics

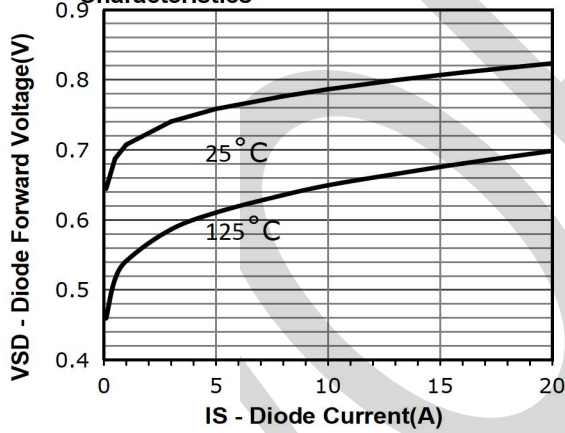
**Fig 1. Output Characteristics (Tj=25°C)**



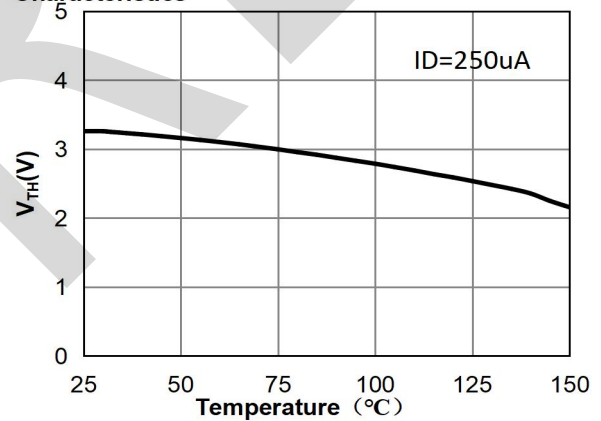
**Fig 2: Transfer Characteristics**



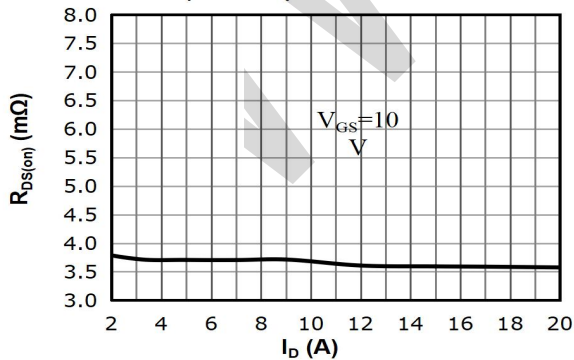
**Fig 3: Body-diode Forward Characteristics**



**Fig 4: VGS(TH) Vs Tj Temperature Characteristics**



**Fig 5: Rds(on) Vs Ids Characteristics (Tc=25°C)**



**Fig 6: Rds(on) vs. Temperature**

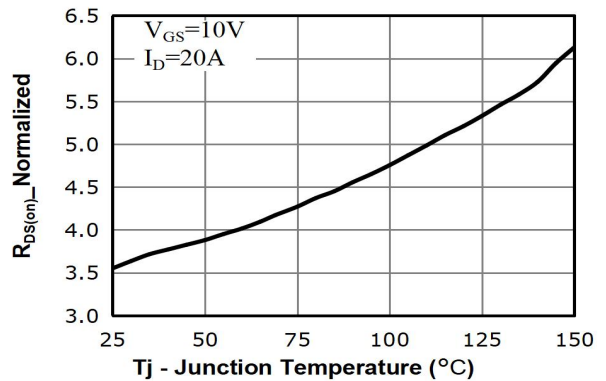


Fig 7: BVDSS vs. Temperature

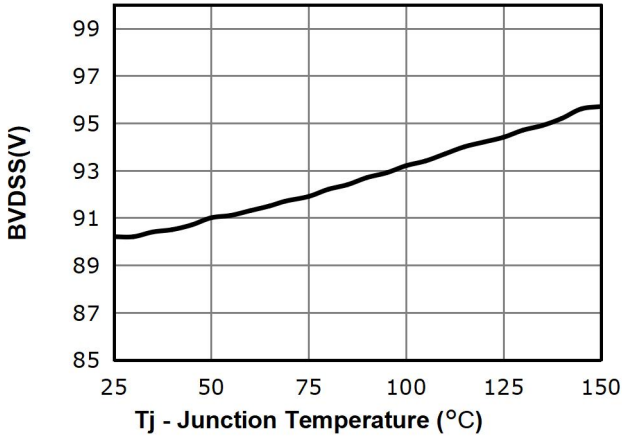


Fig 8: Rds(on) vs Gate Voltage

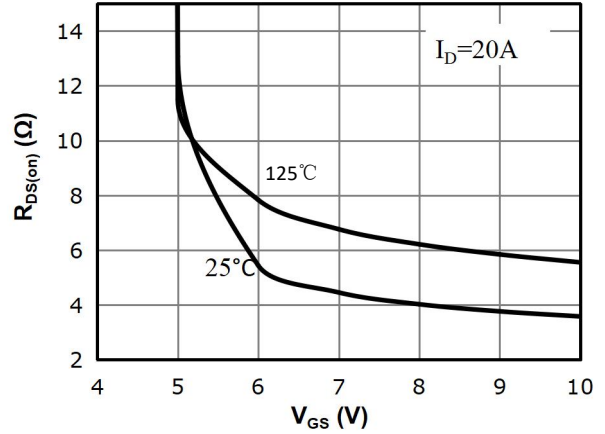


Fig 9: Power Dissipation

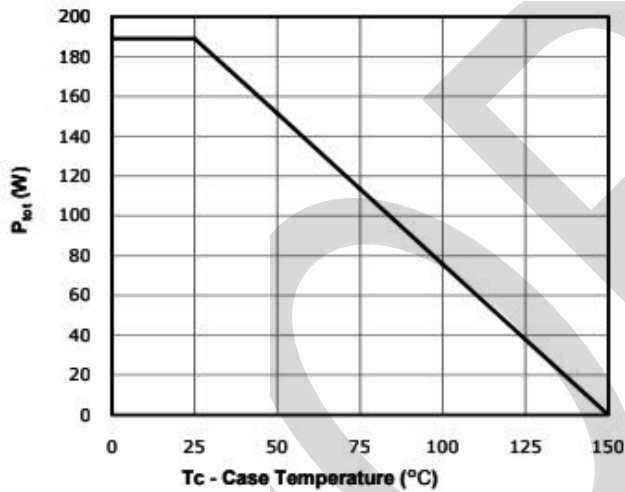


Fig 10: Drain Current Derating

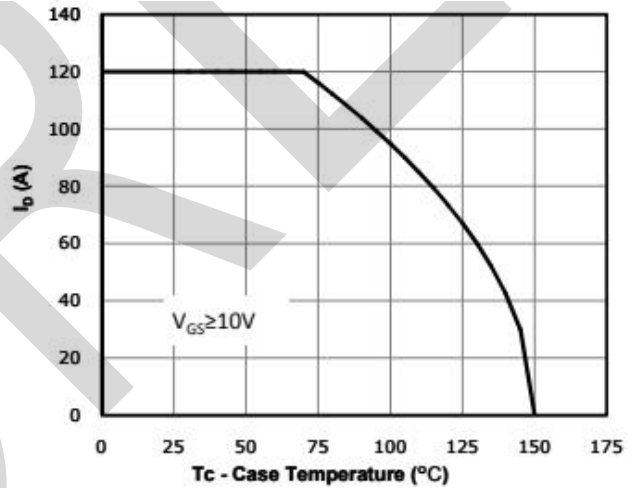


Fig 11: Safe Operating Area

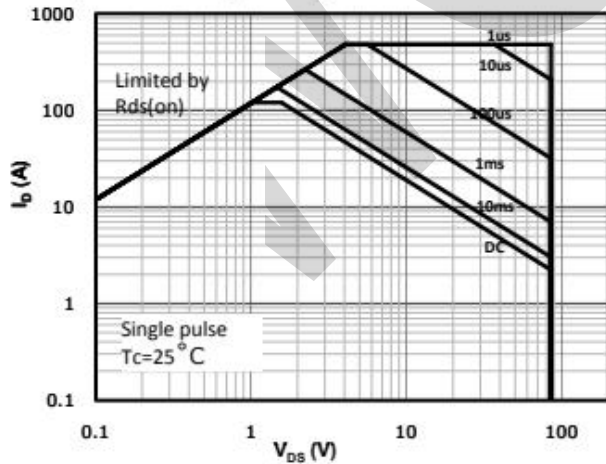
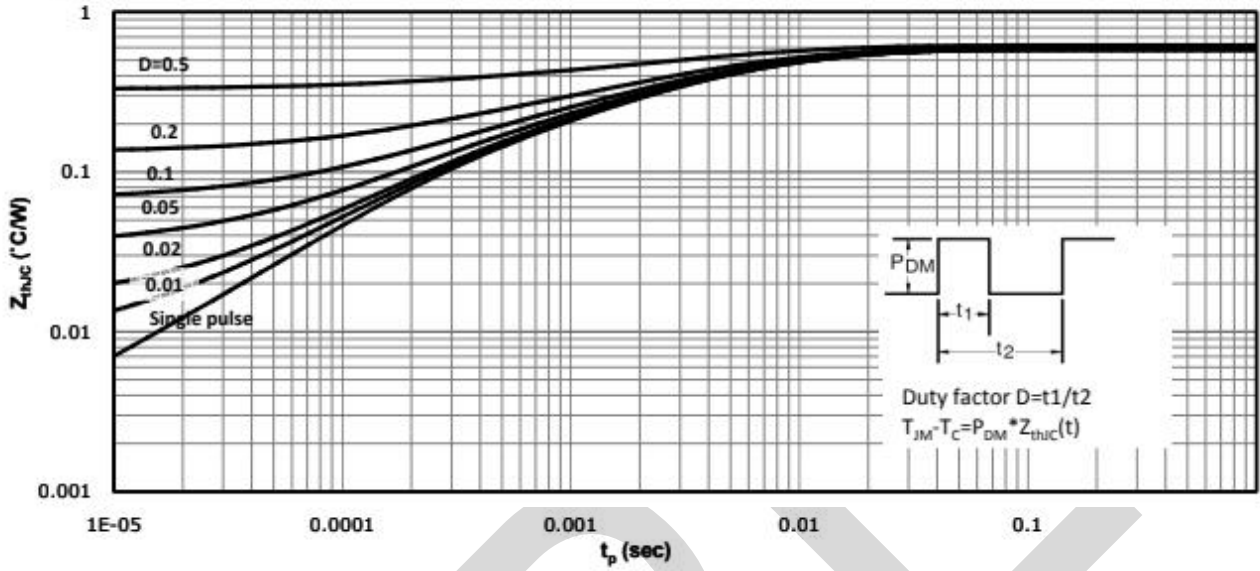


Fig 12: Max. Transient Thermal Impedance



PACKAGE OUTLINE DIMENSIONS

TOLL:(MM)

